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ANSWER 122 OF 575 CA COPYRIGHT 2004 ACS on STN
L5
     132:211720 CA
AN
     Entered STN: 07 Apr 2000
ED
     Manufacture of light-weight hollow wallboard with high strength and low
TI
     production cost
IN
     Wan, Yunzhong
     Loading and Unloading Service Co., Neijiang Vehicle Section, Peop. Rep.
PA
     Faming Zhuanli Shenqing Gongkai Shuomingshu, 4 pp.
so
     CODEN: CNXXEV
DT
     Patent
LA
     Chinese
     ICM C04B020-00
IC
     58-4 (Cement, Concrete, and Related Building Materials)
CC
FAN.CNT 1
                                           APPLICATION NO.
                                                            DATE
     PATENT NO.
                      KIND DATE
                                           CN 1997-107756
                                                             19971103
PΙ
     CN 1178202
                       A
                            19980408
PRAI CN 1997-107756
                            19971103
     The wallboard is prepd. from cement 45-55, expanded material
     10-15, fly ash 30-35, gypsum 4-7,
                                         The manuf. process comprises:
     water 40-55 wt.%, and glass fiber.
     mixing cement with gypsum and fly
     ash, adding expanded material under stirring, mixing with
     water to obtain a micro-foamed slurry (450-560 kg/m3),
     pouring the slurry into a mold, laying a layer of glass fiber,
     putting a mold core into the mold, adding slurry to 2/3 designed
     thickness, laying another layer of glass fiber, adding slurry to
     designed thickness, settling for 1-1.5 h, removing the mold core,
     de-molding after 4 h, and curing. Preferably, the expanded material is
     expanded vermiculite or perlite;.
     light wt hollow wallboard strength prodn cost; cement light wt
ST
     hollow wallboard; expanded vermiculite light wt hollow wallboard; expanded
     perlite light wt hollow wallboard; fly ash
     gypsum glass fiber wallboard; gypsum fly
     ash glass fiber wallboard; glass fiber fly ash
     gypsum wallboard
IT
     Perlite
     RL: PEP (Physical, engineering or chemical process); TEM (Technica
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